

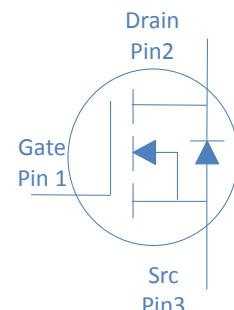
**120V N-Ch Power MOSFET**
**Feature**

- ◊ High Speed Power Smooth Switching, Logic Level
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% R<sub>g</sub> Tested
- ◊ Lead Free

V <sub>DS</sub>	120	V
R <sub>DS(on),typ</sub>	5	mΩ
I <sub>D</sub>	67	A

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ Power Tools
- ◊ UPS
- ◊ Motor Control

**TO-220F**


Part Number	Package	Marking
HGA059N12SL	TO-220F	GA059N12SL

**Absolute Maximum Ratings at T<sub>j</sub>=25°C (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current	I <sub>D</sub>	T <sub>C</sub> =25°C	67	A
		T <sub>C</sub> =100°C	47	
Drain to Source Voltage	V <sub>DS</sub>	-	120	V
Gate to Source Voltage	V <sub>GS</sub>	-	±20	V
Pulsed Drain Current	I <sub>DM</sub>	-	540	A
Avalanche Energy, Single Pulse	E <sub>AS</sub>	L=0.4mH, T <sub>C</sub> =25°C	720	mJ
Power Dissipation	P <sub>D</sub>	T <sub>C</sub> =25°C	58	W
Operating and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-	-55 to 175	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	R <sub>θJC</sub>	2.6	°C/W
Thermal Resistance Junction-Ambient	R <sub>θJA</sub>	60	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

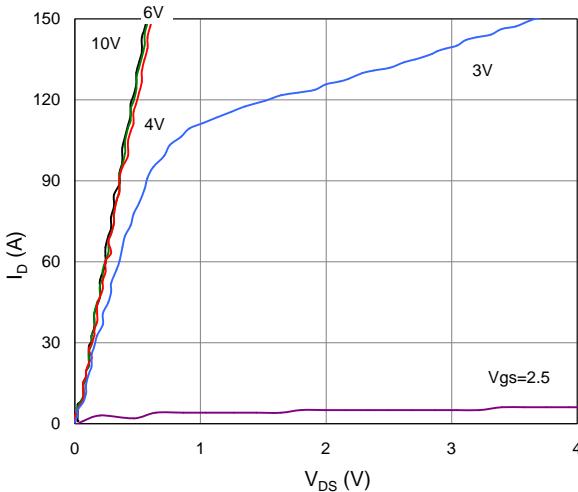
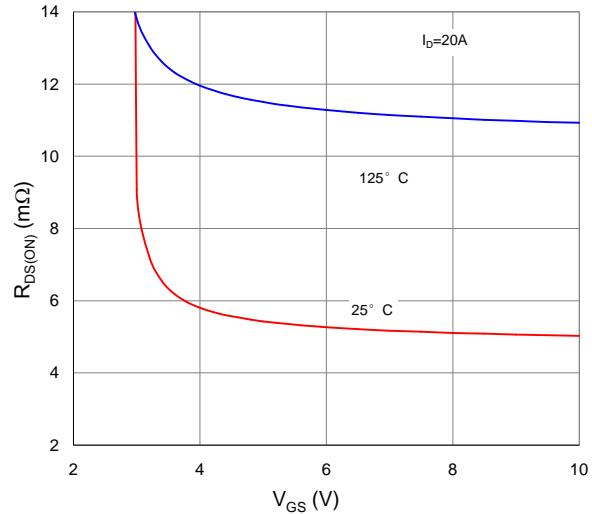
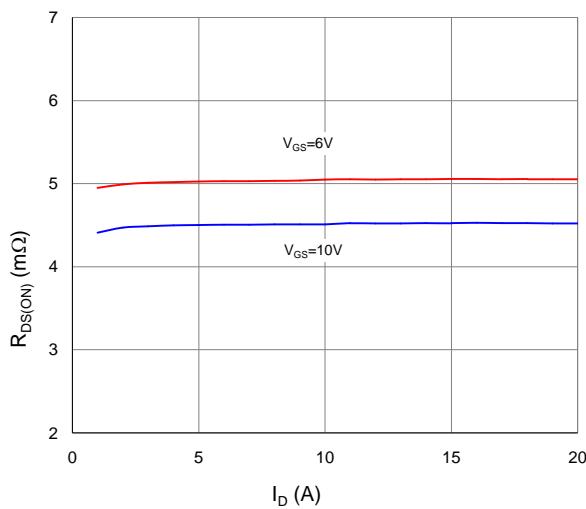
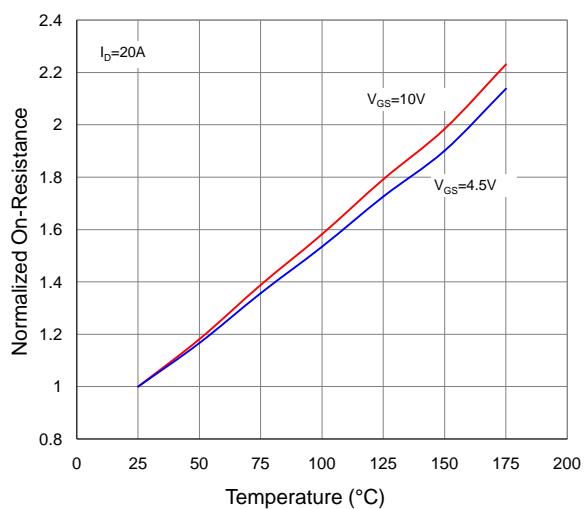
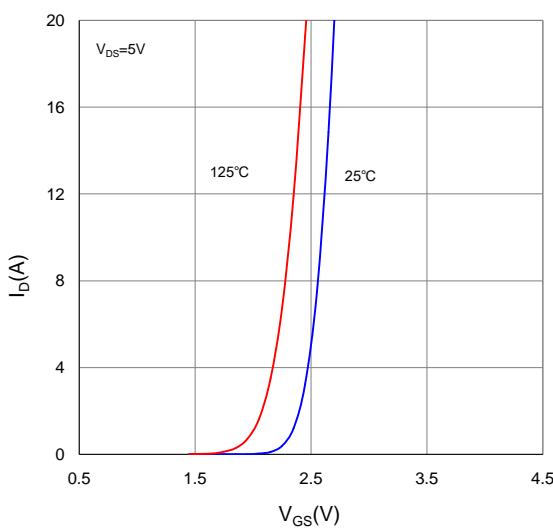
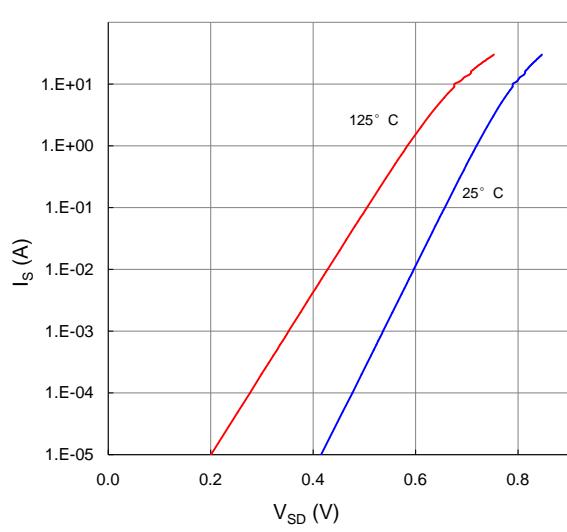
Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	120	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	1.4	1.8	2.4	
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=120\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=120\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	-	5	5.9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=20\text{A}$	-	5.3	7.2	
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	90	-	S
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	0.7	-	$\Omega$

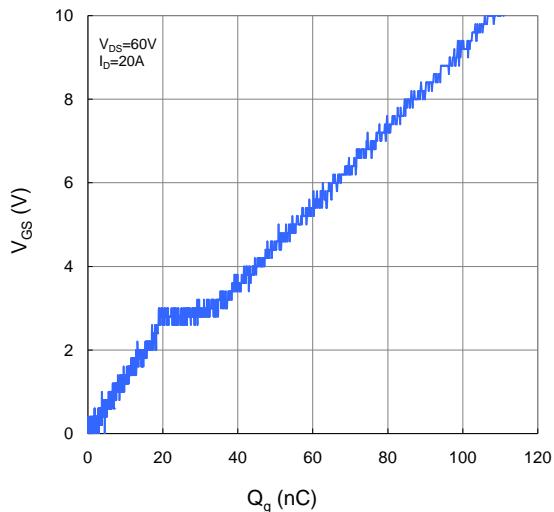
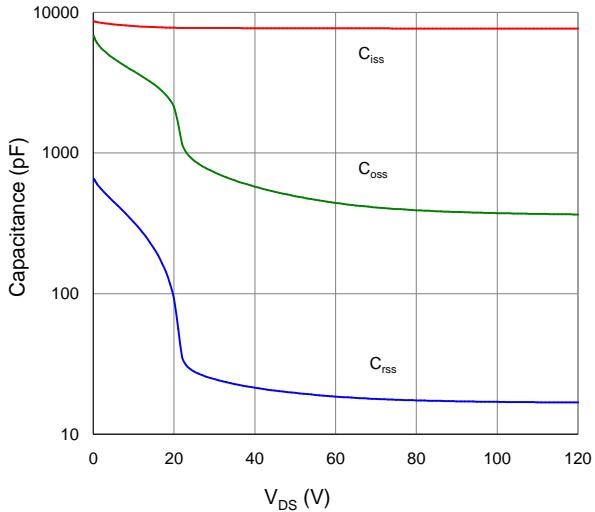
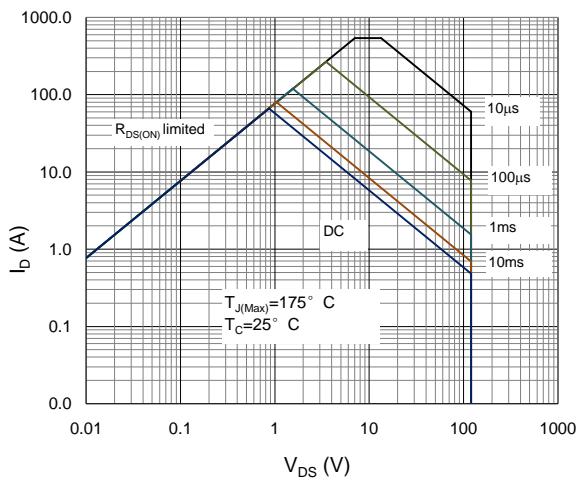
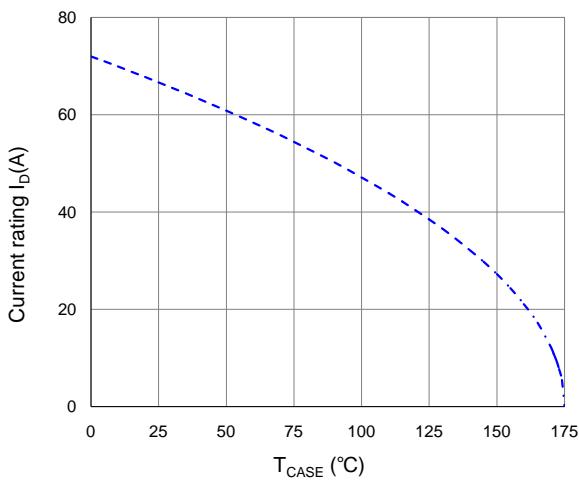
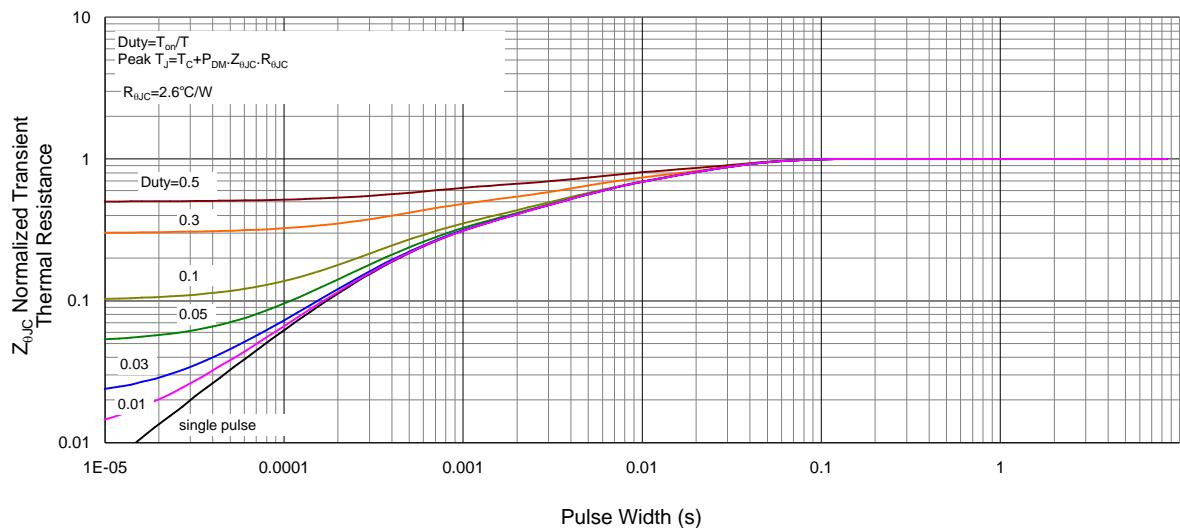
**Dynamic Characteristics**

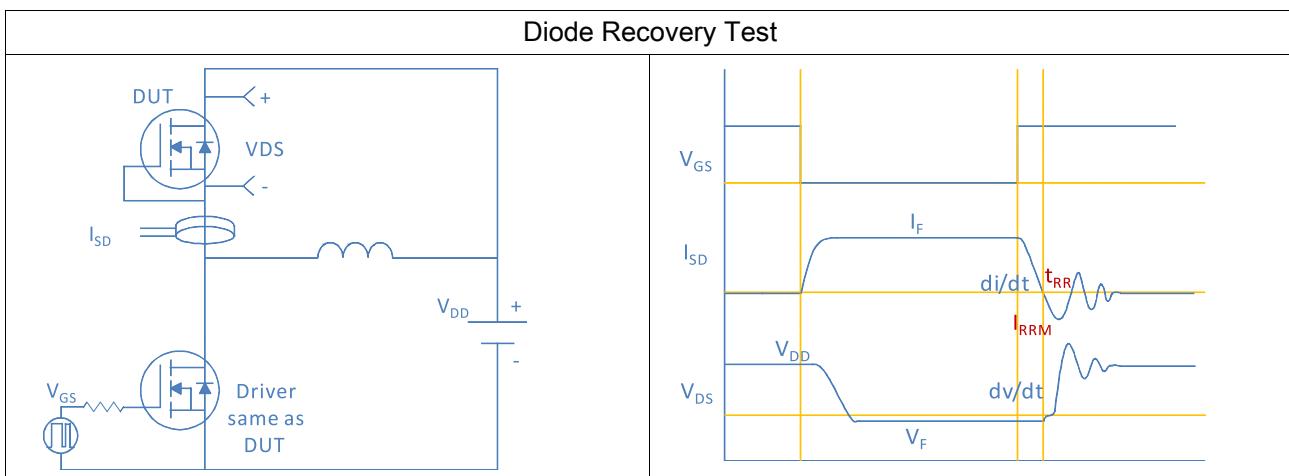
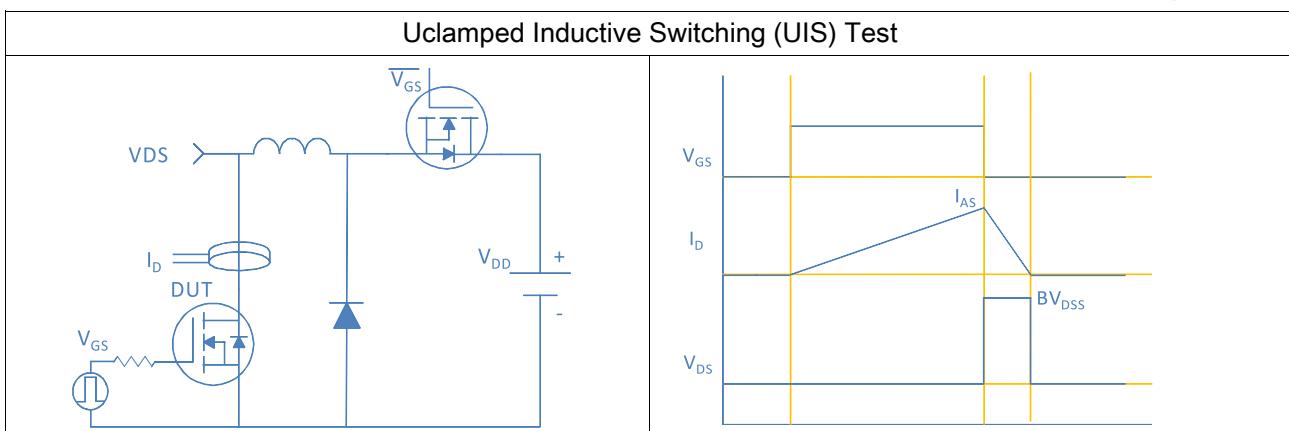
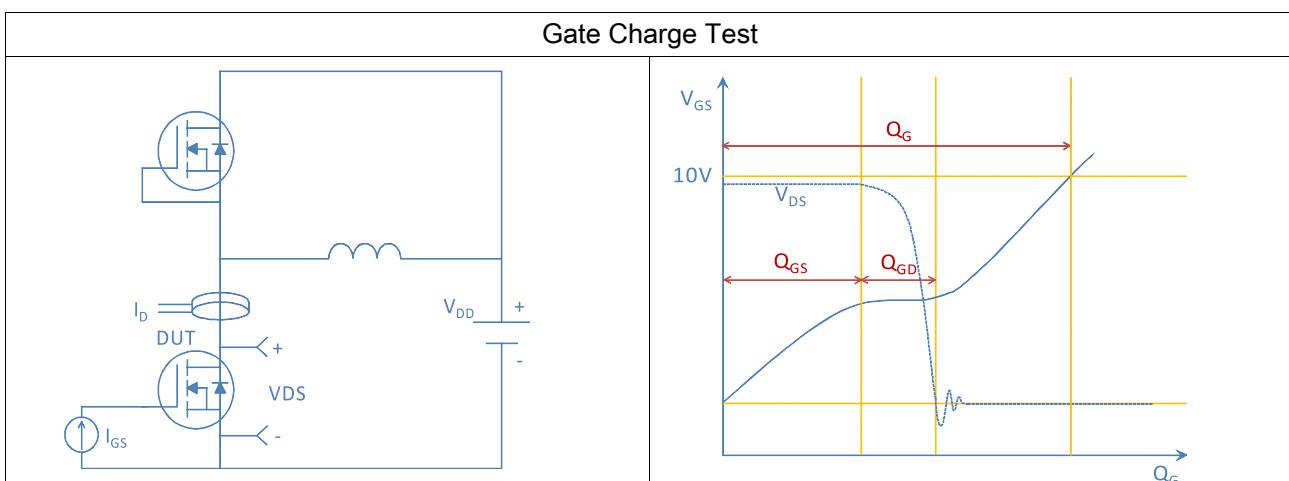
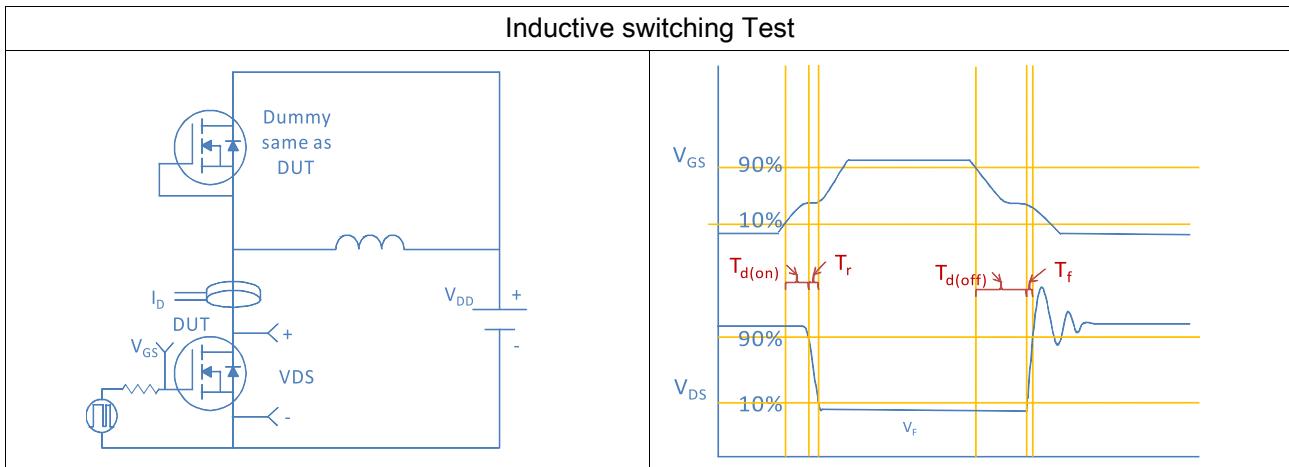
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=60\text{V}, f=1\text{MHz}$	-	7690	-	pF
Output Capacitance	$C_{\text{oss}}$		-	441	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	18.5	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=60\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	110	-	nC
Total Gate Charge	$Q_g(4.5\text{V})$		-	50	-	
Gate to Source Charge	$Q_{\text{gs}}$		-	20	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	34	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=60\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	30	-	ns
Rise time	$t_r$		-	21	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	50	-	
Fall Time	$t_f$		-	17	-	

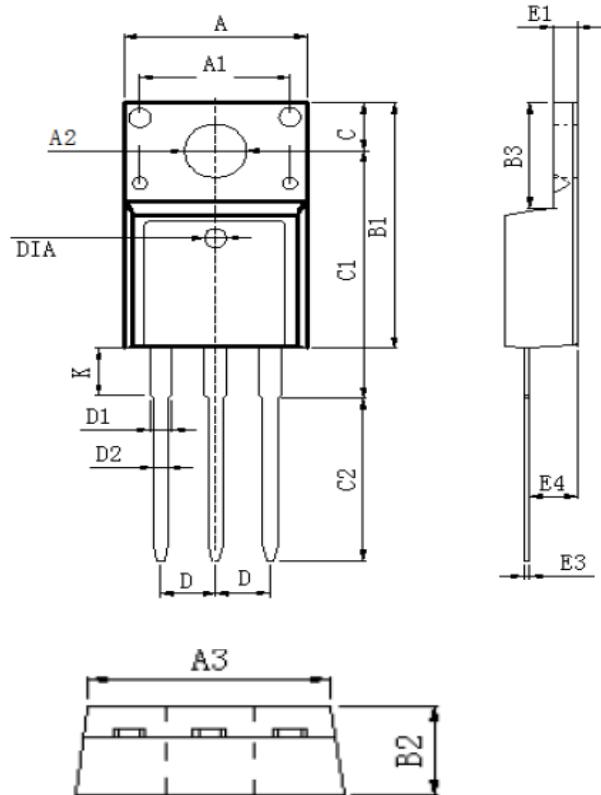
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=60\text{V}, I_F=20\text{A}, dI_F/dt=500\text{A}/\mu\text{s}$	-	80	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	420	-	nC

**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case**




**TO-220F, 3 leads**


DIM	MILLIMETERS
A	10.16±0.3
A1	7.00±0.1
A2	3.3±0.2
A3	9.5±0.2
B1	15.87±0.3
B2	4.7±0.2
B3	6.68±0.4
C	3.3±0.2
C1	12.57±0.3
C2	10.02±0.5
D	2.54±0.05
D1	1.28±0.2
D2	0.8±0.1
K	3.1±0.3
E1	2.54±0.1
E3	0.5±0.1
E4	2.76±0.2
DIA	◎1.5 (deep 0.2)

Unit :mm